



100% Material Declaration Data Sheet BF957

PK184 (v1.1) May 28, 2008

Material Declaration Data Sheet

Average Weight: 18.49 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.695	3.76%
	Silicon	7440-21-3	100.00		0.695	
Solder Bump					0.009	0.05%
	Tin	7440-31-5	63.00		0.006	
	Lead	7439-92-1	37.00		0.003	
Underfill					0.071	0.38%
	Silica	60676-86-0	70.00		0.050	
	Epoxy Resin A	9003-36-5	20.00		0.014	
	Epoxy Resin B	25068-38-6	3.00		0.002	
	Hardener	19900-65-3	7.00		0.005	
Heat Spreader					11.000	59.49%
	Copper	7440-50-8	98.00		10.780	
	Chromium	7440-47-3	2.00		0.220	
Heat Spreader Adhesive					0.085	0.460%
	Silica and other filler materials	Proprietary	70.00		0.060	
	Polymetric Resin	Proprietary	27.00		0.023	
	Silane compound	Proprietary	3.00		0.002	
Substrate					4.784	25.87%
	Copper	7440-50-8	41.40	Metal Layer	1.980	
	Nickel	7440-02-0	0.81	Metal Layer	0.038	
	Gold	7440-57-5	0.18	Metal Layer	0.008	
	Glass Fiber	N/A	4.17		0.200	
	Halogen Fire Retardant	N/A	6.24		0.300	
	BT (core)	N/A	33.30		1.593	
	Solder Mask	N/A	13.90		0.665	
Solder Balls					1.847	9.988%
	Tin	7440-31-5	63.00		1.164	
	Lead	7439-92-1	37.00		0.683	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
9/21/06	1.0	Initial release.
5/28/08	1.1	Updated component weights.